

## DESCRIPTION

The MX2300 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It can be used in a wide variety of applications.

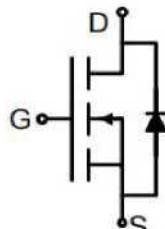
## GENERAL FEATURES

- $V_{DS}=20V$ ,  $I_D=4.5A$
- $R_{DS(ON)}(\text{Typ.})=33m\Omega$  @  $V_{GS}=2.5V$
- $R_{DS(ON)}(\text{Typ.})=27m\Omega$  @  $V_{GS}=4.5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

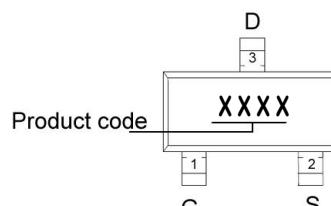
## APPLICATION

- PWM applications
- Load switch

## PINOUT



Schematic diagram



Marking and pin Assignment



SOT-23 top view

## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MX2300	-55°C to 150°C	SOT-23	3000

## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	4.5	A
Pulsed Drain Current <sup>(Note1)</sup>	$I_{DM}$	13.5	A
Maximum Power Dissipation	$P_D$	1.25	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

## THERMAL RESISTANCE

Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	100	°C/W
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.


**ELECTRICAL CHARACTERISTICS**( $T_A=25^\circ C$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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**Off Characteristics**

Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 100$	nA

**On Characteristics<sup>(Note 3)</sup>**

Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.65	1.2	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=2.5V, I_D=4A$	-	33	40	$m\Omega$
		$V_{GS}=4.5V, I_D=4.5A$	-	27	33	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=10V, I_D=4A$	-	10	-	S

**Dynamic Characteristics<sup>(Note 4)</sup>**

Input Capacitance	$C_{iss}$	$V_{DS}=8V, V_{GS}=0V, F=1.0MHz$	-	500	-	pF
Output Capacitance	$C_{oss}$		-	300	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	140	-	pF

**Switching Characteristics<sup>(Note 4)</sup>**

Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=1A, V_{GS}=4.5V, R_{GEN}=6\Omega$	-	20	-	nS
Turn-on Rise Time	$t_r$		-	18	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	60	-	nS
Turn-Off Fall Time	$t_f$		-	28	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=10V, I_D=3A, V_{GS}=4.5V$	-	10	-	nC
Gate-Source Charge	$Q_{gs}$		-	2.3	-	nC
Gate-Drain Charge	$Q_{gd}$		-	2.9	-	nC

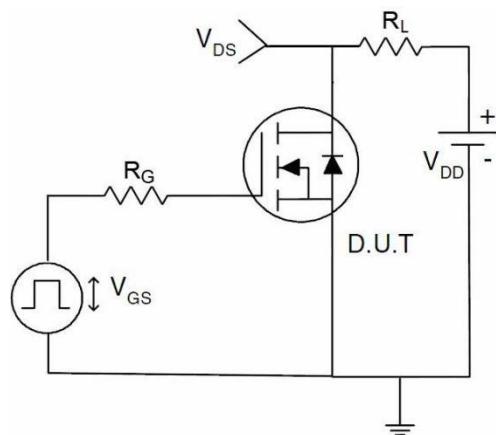
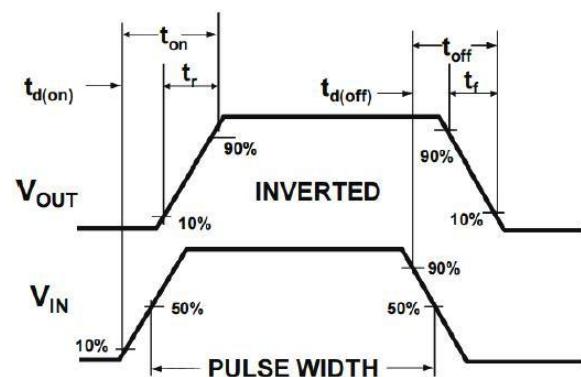
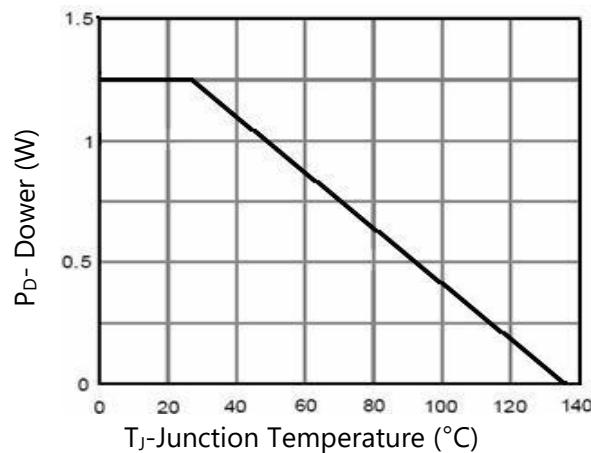
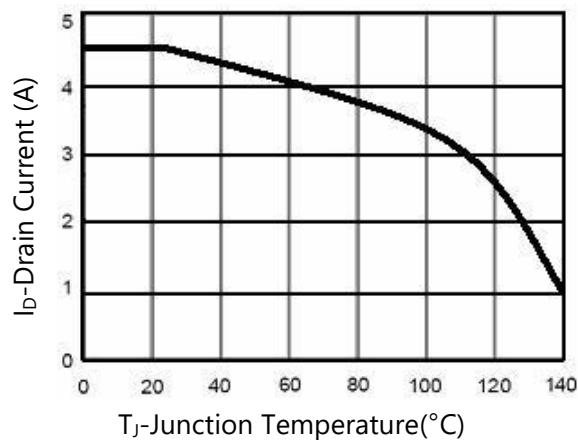
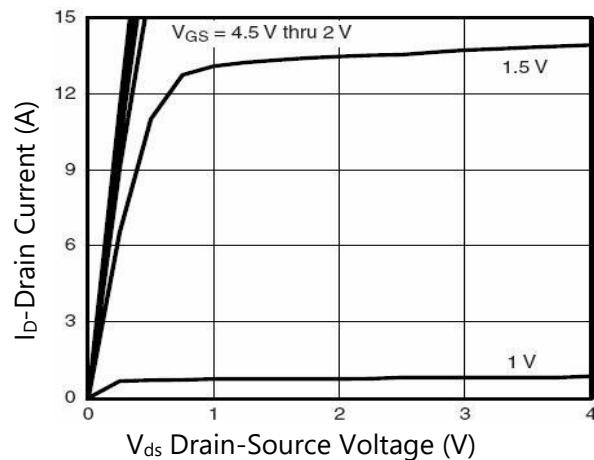
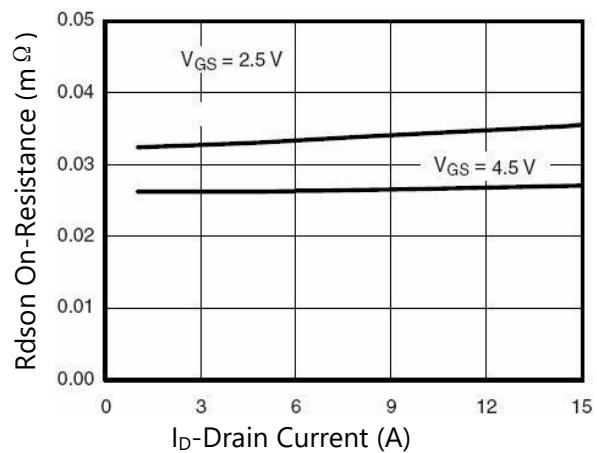
**Drain-Source Diode Characteristics**

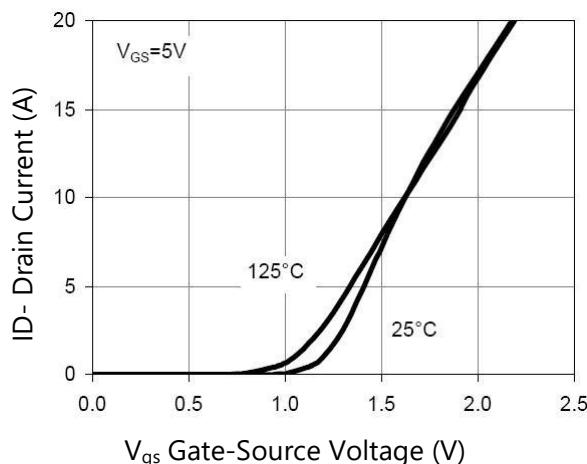
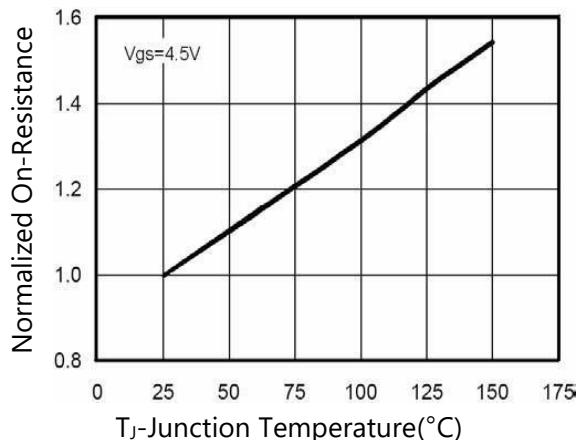
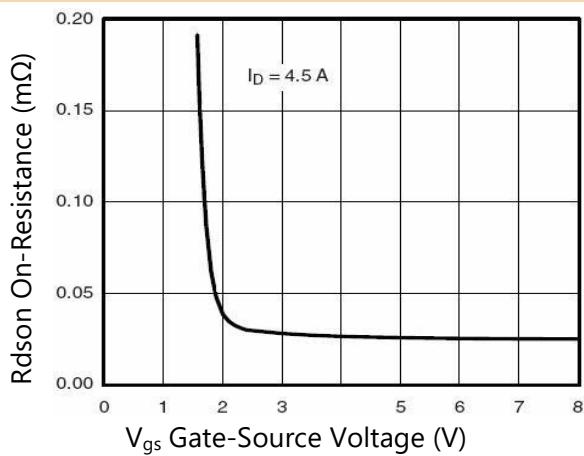
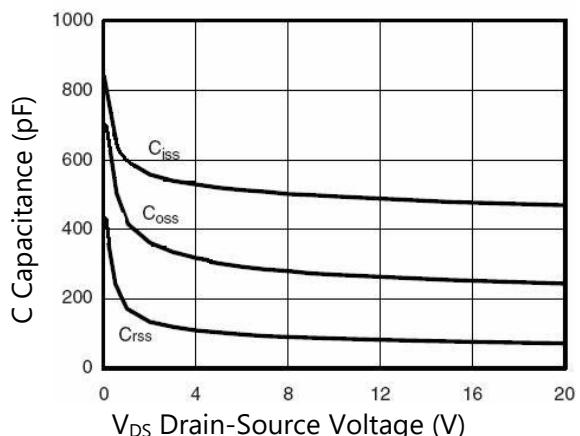
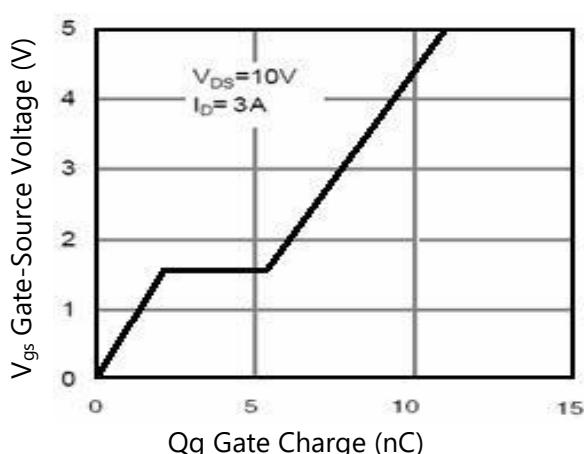
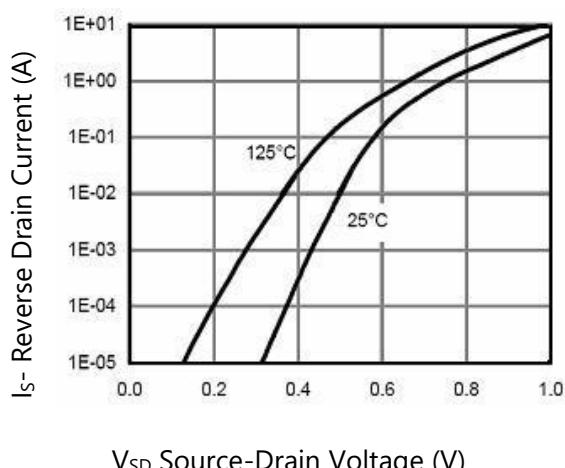
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_S$		-	-	1	A

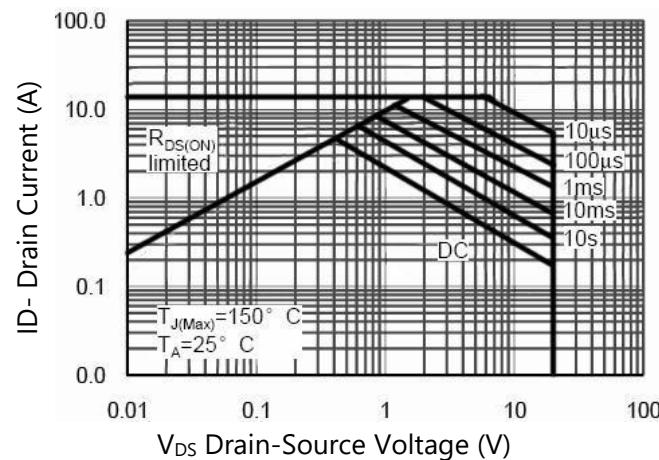
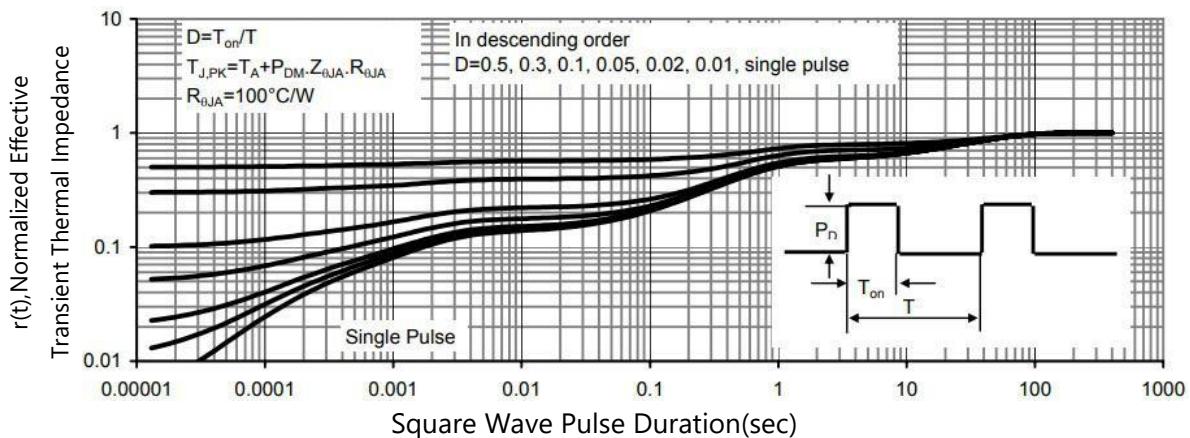
Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

Note 3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .

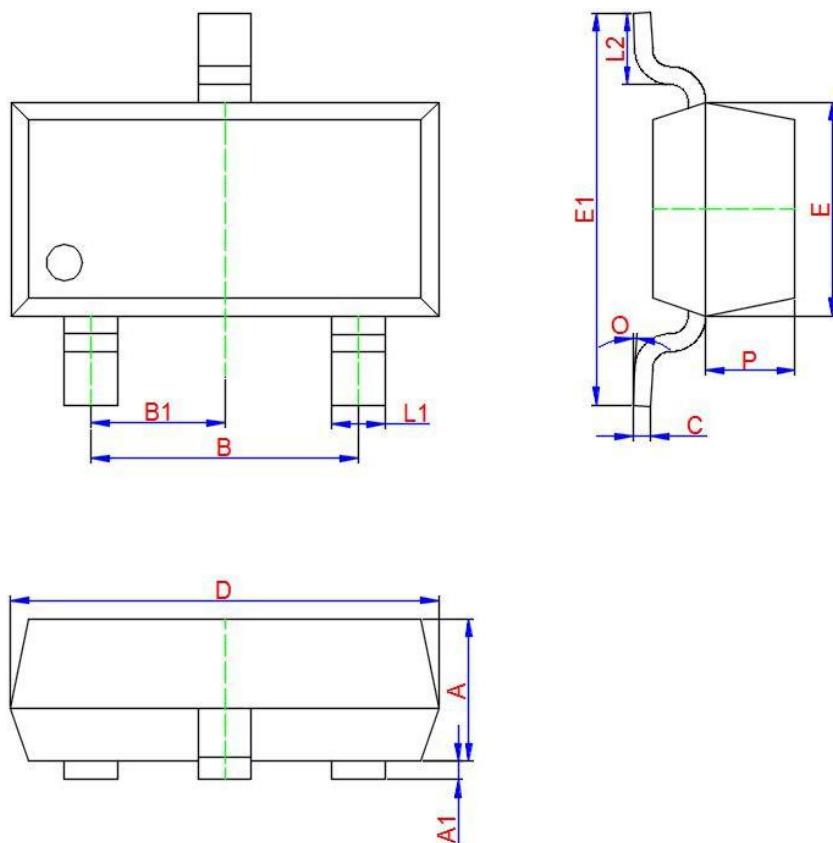
Note 4. Guaranteed by design, not subject to product.


**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**
**Figure 1. Switching Test Circuit**

**Figure 2. Switching Waveform**

**Figure 3. Power Dissipation**

**Figure 4. Drain Current**

**Figure 5. Output Characteristics**

**Figure 6. R<sub>dson</sub> vs Drain Current**



**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**
**Figure 7. Transfer Characteristics**

**Figure 8. R<sub>dson</sub> vs Junction Temperature**

**Figure 9. R<sub>dson</sub> vs V<sub>gs</sub>**

**Figure 10. Capacitance vs V<sub>DS</sub>**

**Figure 11. Gate Charge**

**Figure 12. Source- Drain Diode Forward**



**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**
**Figure 13. Safe Operation Area**

**Figure 14. Normalized Maximum Transient Thermal Impedance**


## PACKAGE INFORMATION

**SOT-23**


Symbol	Dimensions in Millimeters		
	Min	Typ.	Max
A	0.900	1.000	1.100
A1	0.000	0.050	0.100
L1	0.300	0.400	0.500
C	0.100	0.110	0.120
D	2.800	2.900	3.000
E	1.250	1.300	1.350
E1	2.250	2.400	2.550
B	1.800	1.900	2.000
B1	0.950 TYP.		
L2	0.200	0.350	0.450
P	0.550	0.575	0.600
O	0°	4°	8°